DESCRIPTION

Title of Invention

~~FILM-LIKE TRANSPARENT ADHESIVE AND~~ INFRARED SENSOR MODULE

TECHNICAL FIELD

[0001]

The present invention relates to a film-like transparent adhesive and an infrared sensor module.

Priority is claimed on Japanese Patent Application No. 2017-163632, filed on August 28, 2017, the amount of which is incorporated herein by reference.

BACKGROUND ART

[0002]

As a cover member for an infrared sensor such as a human sensor, a cover glass member having high light transmittance in the infrared region has been proposed (Patent Document 1). In an infrared sensor, a cover glass member is provided with a concave portion and is fixed to a frame portion of the infrared sensor as in, for example, Patent Document 2.

Citation List

Patent Literature

[0003]

[Patent Document 1] Japanese Unexamined Patent Application, First Publication No. 2016-040220

CLAIMS

What is claimed is:

1. An infrared sensor module that is formed by bonding an infrared light receiving element having an infrared light receiving portion and a glass wafer by curing using a thermosetting film-like transparent adhesive,

wherein the infrared light receiving portion is provided to receive infrared light that has passed through the glass wafer and the film-like transparent adhesive after curing,

wherein the thermosetting film-like transparent adhesive contains an acrylic resin, an epoxy resin (b1) and a thermosetting agent (b2),

wherein the light transmittance of the thermosetting film-like transparent adhesive after curing at a wavelength of 800 to 2000 nm is all 80% or more~~A film-like transparent adhesive that is a thermosetting or energy ray-curable film-like transparent adhesive and has a light transmittance of 80% or more at a wavelength of 800 nm after curing~~.

~~2. The film-like transparent adhesive according to claim 1,~~

~~wherein all light transmittances at wavelengths of 800 to 2,000 nm after curing are 80% or more.~~

2~~3~~. The infrared sensor module~~film-like transparent~~ adhesive according to claim 1~~ or 2~~,

wherein the~~a~~ light transmittance of the thermosetting film-like transparent adhesive after curing at a wavelength of 850 nm~~ after curing~~ is 90% or more.

3~~4~~. The infrared sensor module ~~film-like transparent~~ adhesive according to ~~any one of~~ claim~~s~~ 1 or~~to~~ 2~~3~~ comprising:

wherein the thermosetting film-like transparent adhesive contains a filler,

wherein the filler has an average particle diameter of 450 nm or less.

~~5. An infrared sensor module that is formed by bonding an infrared light receiving element having an infrared light receiving portion and a glass wafer by curing using the film-like transparent adhesive according to any one of claims 1 to 4,~~

~~wherein the infrared light receiving portion is provided to receive infrared light that has passed through the glass wafer and the film-like transparent adhesive after curing~~